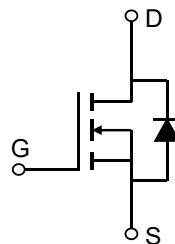


### Description

#### Features

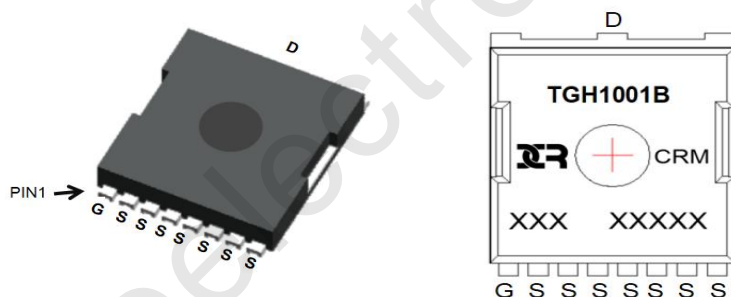
- 100V, 420A  
 $R_{DS(ON)}$  Typ = 1.13mΩ @  $V_{GS} = 10V$
- Advanced Split Gate Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- 100% UIS TESTED!
- 100%  $\Delta V_{ds}$  TESTED!



Schematic Diagram

#### Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

#### Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMTGH1001B	CRMTGH1001B	TOLL	TAPING	13"	2000	10000

#### Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	100	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ C$	420 A
		$T_C = 100^\circ C$	252 A
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	1680	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	1225	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ C$	390 W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.32	$^\circ C/W$
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	$^\circ C$

### Electrical Characteristics ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	100	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
On Characteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	3	3.5	4.5	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A	-	1.13	1.4	mΩ
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 50V, f = 100KHz	-	10960	-	pF
C <sub>oss</sub>	Output Capacitance		-	3713	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	74	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to 10V V <sub>DS</sub> = 50V, I <sub>D</sub> = 100A	-	172	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	57.9	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	38.6	-	nC
Switching Characteristics						
t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 50V I <sub>D</sub> = 100A, R <sub>GEN</sub> = 5Ω	-	35	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	90	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime		-	95	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	105	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	420	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	1680	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I <sub>F</sub> = 100A, di/dt = 100A/us	-	10000	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	200	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2.  $E_{AS}$  condition: Starting  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 50\text{V}$ ,  $V_G = 10\text{V}$ ,  $R_G = 25\text{ohm}$ ,  $L = 0.5\text{mH}$ ,  $I_{AS} = 70\text{A}$
  3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

## Test Circuit

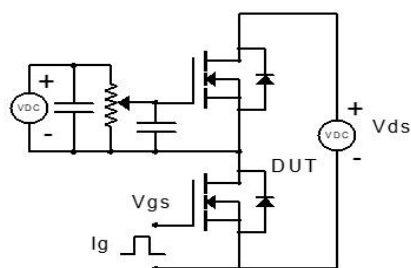


Figure 1: Gate Charge Test Circuit & Waveform

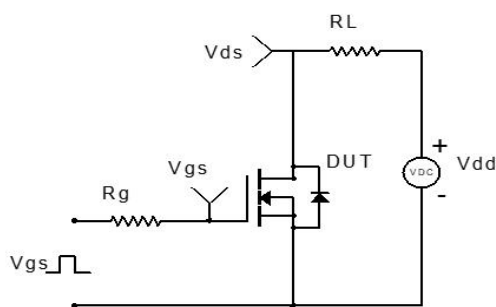


Figure 2: Resistive Switching Test Circuit & Waveform

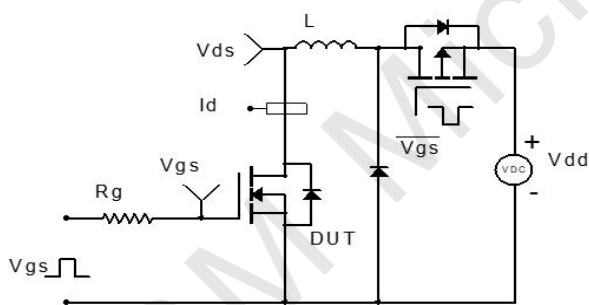


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

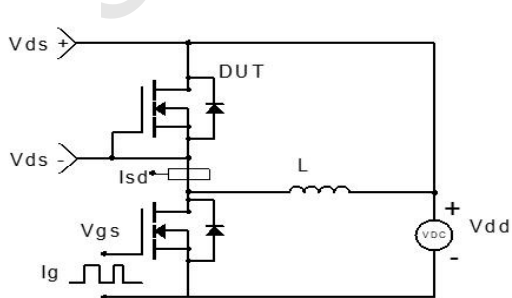
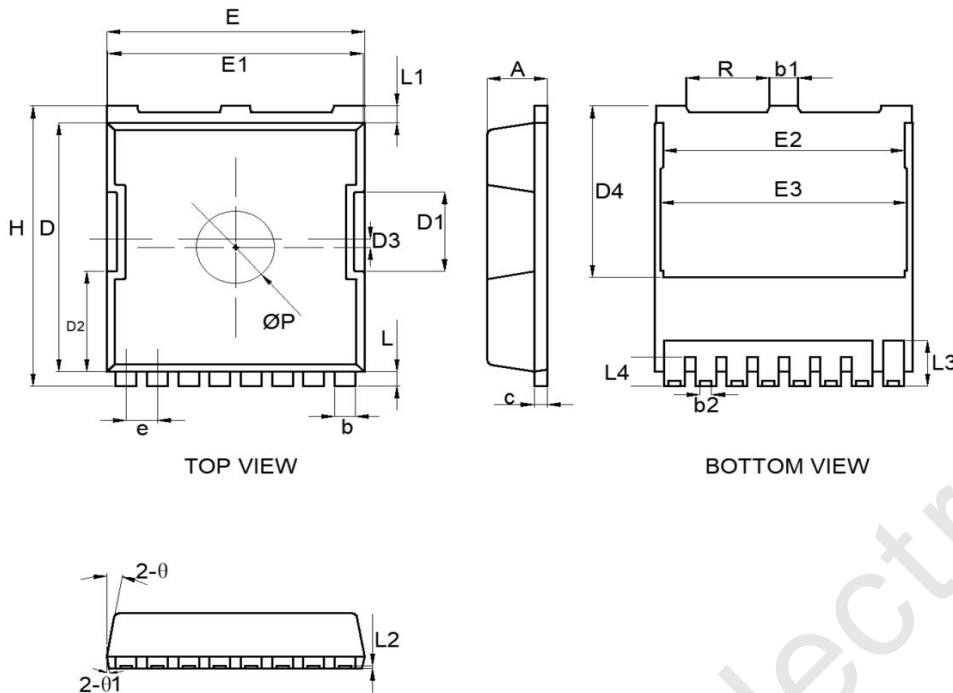


Figure 4: Diode Recovery Test Circuit & Waveform

### Package Mechanical Data(TOLL)



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.20	2.30	2.40
b	0.60	0.70	0.80
b1	1.10	1.20	1.30
b2	0.36 REF.		
c	0.40	0.50	0.60
D	10.30	10.40	10.50
D1	3.20	3.30	3.40
D2	4.08	4.18	4.28
D3	0.53	0.63	0.73
D4	7.35 REF.		
E	9.80	9.90	10.00
E1	9.70	9.80	9.90
E2	8.80 REF.		
E3	8.95 REF.		
e	1.20 BSC.		
H	11.50	11.70	11.90
L	0.50	0.60	0.70
L1	0.60	0.70	0.80
L2	0.10 REF.		
L3	1.27 REF.		
L4	1.10 REF.		
P	2.00	3.00	4.00
R	3.00	3.10	3.20
θ	7°	9°	11°
θ1	3°	5°	7°

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